

### **Technical Data Sheet**

#### **Product Description**

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness options to easily solve any heat related issue. EVERTHERM pads are naturally tacky and can be cut to any size or shape for easy installation. EVERTHERM pads are designed and engineered to achieve the highest level of thermal management to protect today's most advanced electronics.





### **Material Properties**

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation
   performance
- Good flexibility and high compression ratio

## **EVSF800**

0149	
200 x 300mm equest.)	



Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

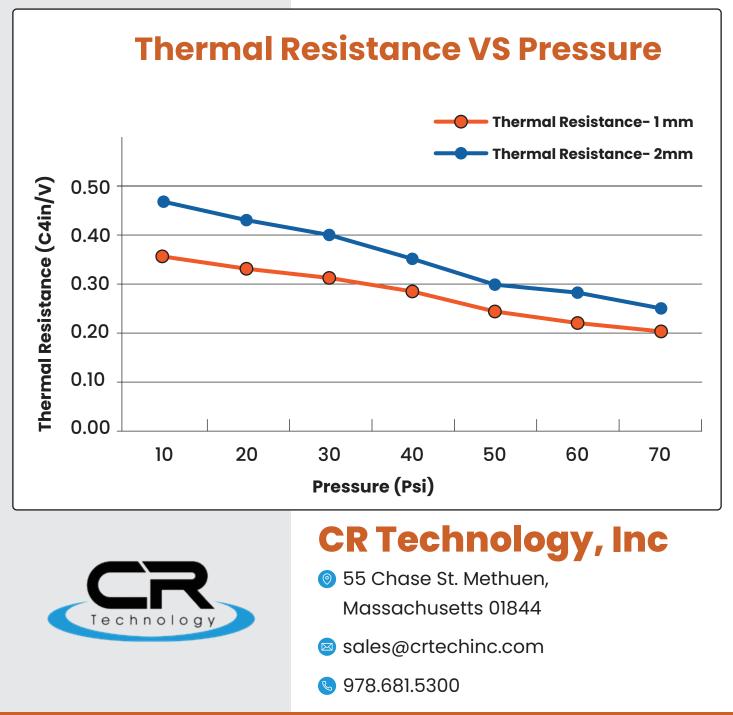


# **EVSF800**

## Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- ✓ LED lighting equipment
- Section Components like:

LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



**Note:** The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.